

Ceramic Plate Series Thermoelectric Cooler

The CP14-127-045-L1-EP-W4.5 is a high-performance and highly reliable standard Thermoelectric Cooler. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics. It has a maximum Q_c of 71.3 Watts when $\Delta T = 0$ and a maximum ΔT of 70.5 °C at $Q_c = 0$.

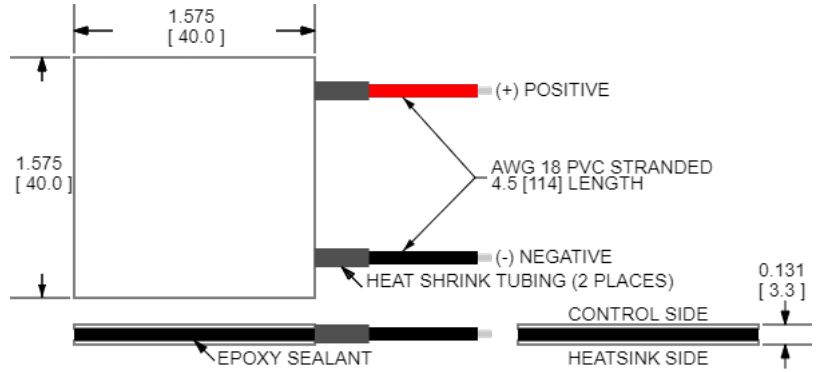


Features

- Compact geometric sizes
- DC Operation
- RoHS-compliant

Applications

- Thermoelectric Coolers for Reagent Storage
- Thermoelectric Coolers for Handheld Cosmetic Lasers
- Cooling for Centrifuges
- Heads-Up Displays, Imaging Sensors
- Peltier Cooling for Machine Vision

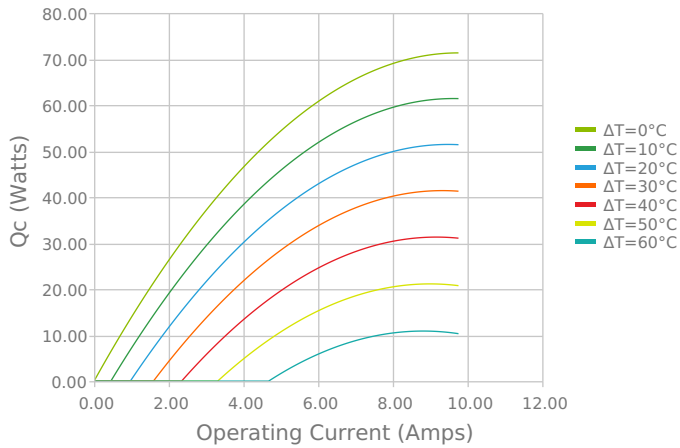


CERAMIC MATERIAL: Al_2O_3
 SOLDER CONSTRUCTION: 138°C, BiSn
 INCHES [MM]
 Note: Allow 0.020 in [0.5 mm] around perimeter of the thermoelectric cooler and lead wire attachment to accommodate sealant

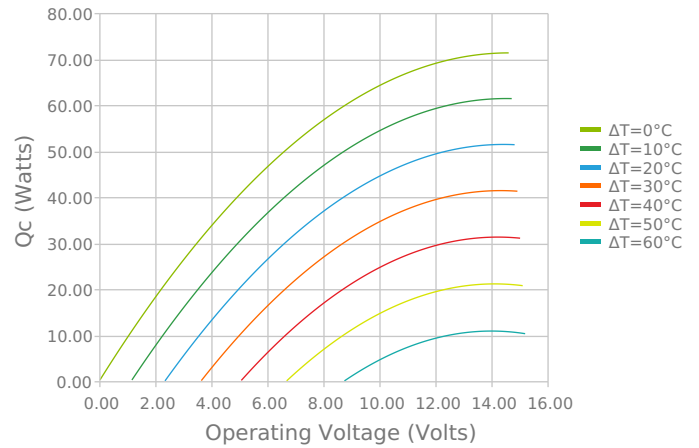
ELECTRICAL AND THERMAL PERFORMANCE

For maximum performance, be sure to orient the CONTROL side of the TEC against the application to be managed and the HEATSINK side against the heat sink or other heat rejection method. The CONTROL side is always opposite the side with lead attachments. Lead attachment is a passive heat loss and less impactful if located on the side that attaches to the heat exchanger.

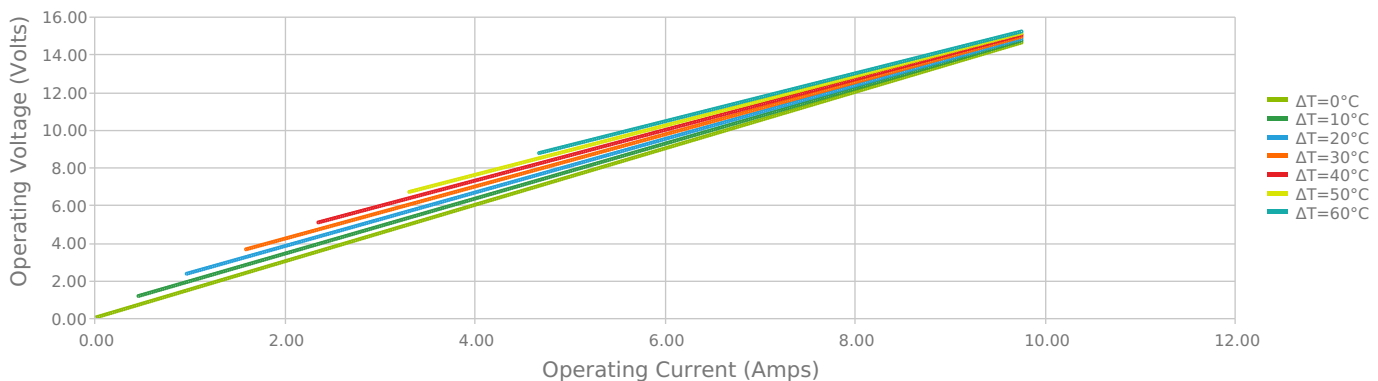
Heat Pumped at Cold Side
 $T_{hot} = 27\text{ °C}$



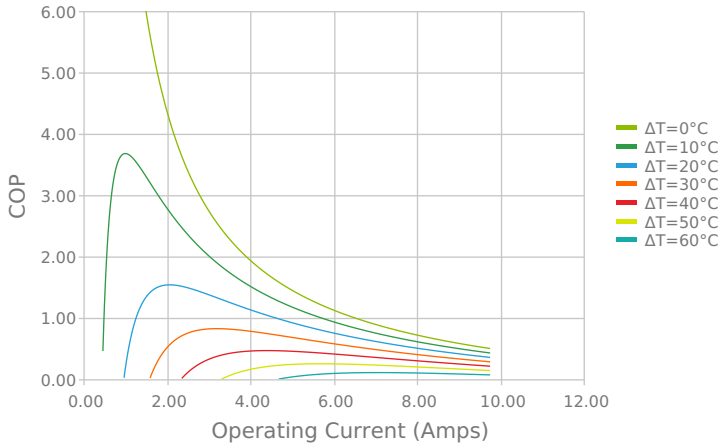
Heat Pumped at Cold Side
 $T_{hot} = 27\text{ °C}$



Current vs Voltage (I vs V)
 $T_{hot} = 27\text{ °C}$



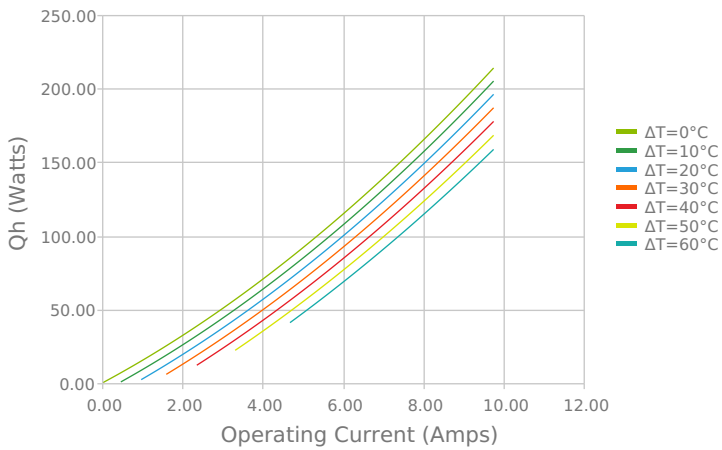
Coefficient of Performance (COP = Q_c/P_{in})
 $T_{hot} = 27\text{ }^\circ\text{C}$



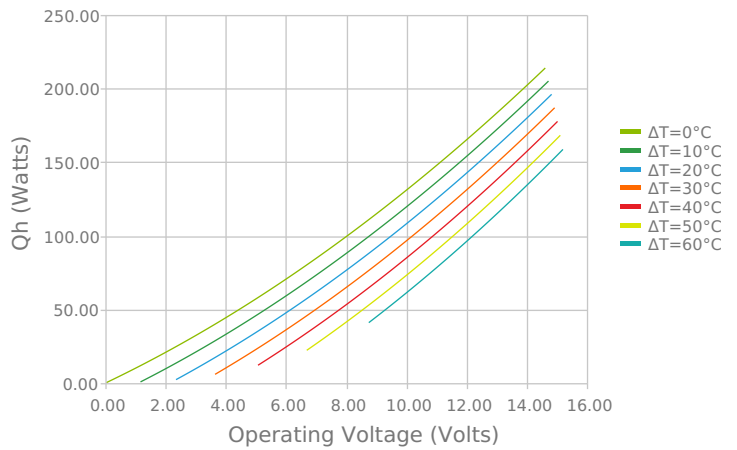
Coefficient of Performance (COP = Q_c/P_{in})
 $T_{hot} = 27\text{ }^\circ\text{C}$



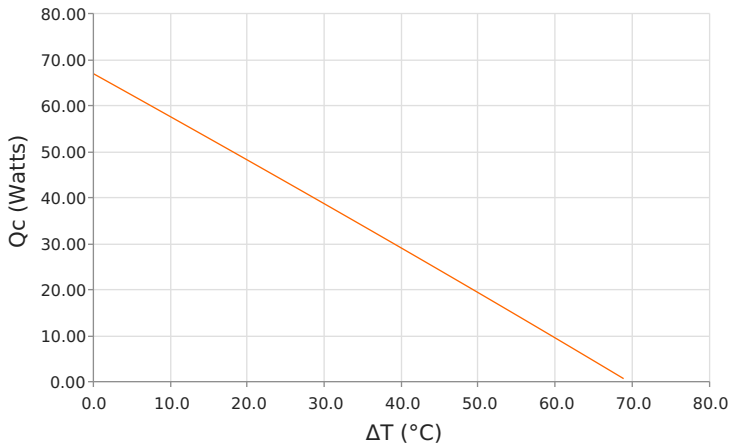
Total Heat Dissipated at Hot Side ($Q_h=Q_c+P_{in}$)
 $T_{hot} = 27\text{ }^\circ\text{C}$



Total Heat Dissipated at Hot Side ($Q_h=Q_c+P_{in}$)
 $T_{hot} = 27\text{ }^\circ\text{C}$



Heat Pumped at Cold Side (Q_c)
 $T_{hot} = 27\text{ }^\circ\text{C}$ | Current = 7.3 Amps



Coefficient of Performance (COP = Q_c/P_{in})
 $T_{hot} = 27\text{ }^\circ\text{C}$ | Current = 7.3 Amps



SPECIFICATIONS*

| Hot Side Temperature | 27.0 °C | 35.0 °C | 50.0 °C |
|---|--------------|------------|------------|
| Qcmax ($\Delta T = 0$) | 71.3 Watts | 73.5 Watts | 77.3 Watts |
| ΔT_{max} ($Q_c = 0$) | 70.5°C | 73.5°C | 78.8°C |
| I_{max} (I @ ΔT_{max}) | 8.6 Amps | 8.6 Amps | 8.5 Amps |
| V_{max} (V @ ΔT_{max}) | 13.9 Volts | 14.4 Volts | 15.4 Volts |
| Module Resistance | 1.50 Ohms | 1.56 Ohms | 1.68 Ohms |
| Max Operating Temperature | 80 °C | | |
| Weight | 20.0 gram(s) | | |

* Specifications reflect thermoelectric coefficients updated March 2020

FINISHING OPTIONS

| Suffix | Thickness | Flatness / Parallelism | Hot Face | Cold Face | Lead Length |
|--------|--------------------------------------|--|----------|-----------|---------------------|
| L1 | 3.327 ±0.025 mm 0.131 ± 0.0010 in | 0.025 mm / 0.025 mm 0.001 in / 0.001 in | Lapped | Lapped | 114.3 mm 4.50 in |

SEALING OPTIONS

| Suffix | Sealant | Color | Temp Range | Description |
|--------|---------|-------|--------------|--|
| EP | Epoxy | Black | -55 to 150°C | Low density syntactic foam epoxy encapsulant |

NOTES

1. Max operating temperature: 80°C
2. Do not exceed I_{max} or V_{max} when operating module
3. Reference assembly guidelines for recommended installation
4. Solder tinning also available on metallized ceramics

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